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Title: SYSTEM FOR FABRICATING AN INTEGRATED CIRCUIT PACKAGE ON A PRINTED CIRCUIT BOARD

Inventors: Yong Gang Jin, et al. Docket No.: 27-012 Contact: Mikio Ishimaru (4

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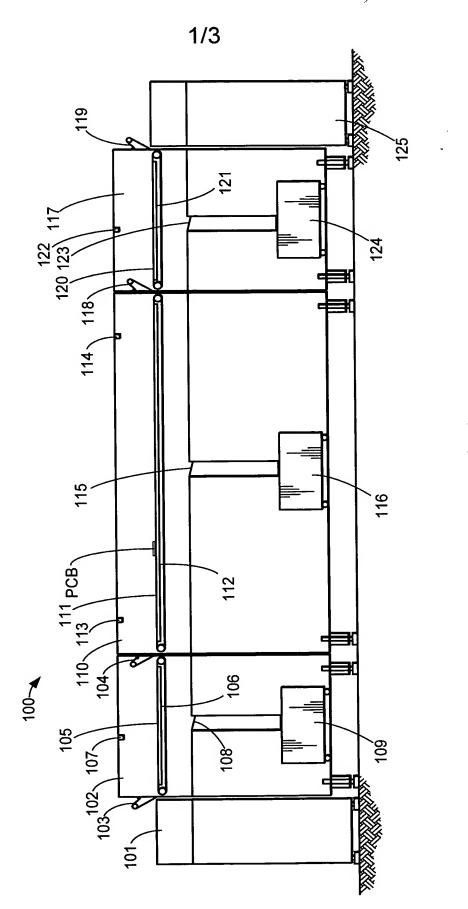


FIG. 1

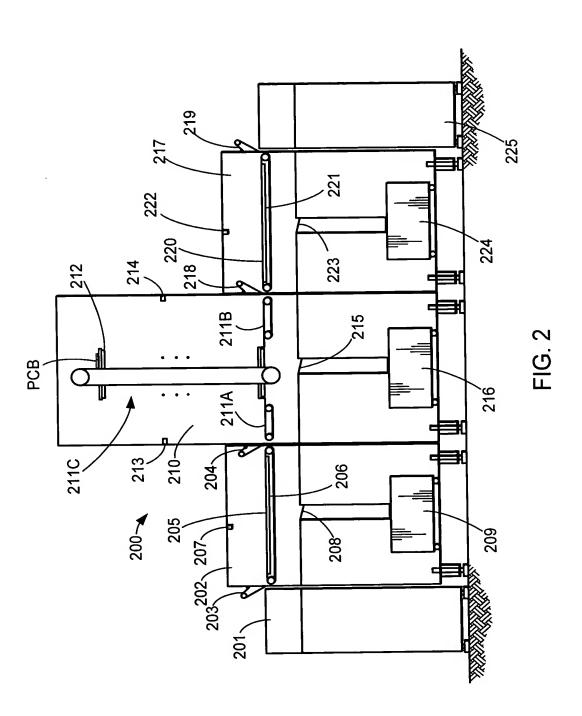
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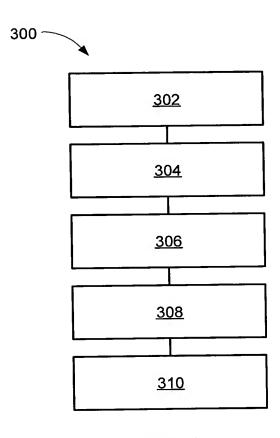


FIG. 3